

# TUSB322I USB Type-C™ Configuration Channel Logic and Port Control with VCONN

## 1 Features

- USB Type-C™ Specification 1.1
- Backward Compatible with USB Type-C Specification 1.0
- Supports Up to 3 A of Current Advertisement and Detection
- Mode Configuration
  - Host Only – DFP/Source (I<sup>2</sup>C Mode only)
  - Device Only – UFP/Sink (I<sup>2</sup>C Mode only)
  - Dual Role Port – DRP
- Channel Configuration (CC)
  - Attach of USB Port Detection
  - Cable Orientation Detection
  - Role Detection
  - Type-C Current Mode (Default, Medium, High)+u
- V<sub>BUS</sub> Detection
- I<sup>2</sup>C or GPIO Control
- VCONN Support for Active Cables
- Cable Detection and Direction Control for External Switches
- Role Configuration Control through I<sup>2</sup>C
- Supply Voltage: 4.5 V to 5.5 V
- Low Current Consumption
- Industrial Temperature Range of –40 to 85°C

## 2 Applications

- Host, Device, Dual Role Port Applications
- Mobile Phones
- Tablets and Notebooks
- USB Peripherals

## 3 Description

The TUSB322I device enables USB Type-C ports with the configuration channel (CC) logic required for Type-C ecosystems. The TUSB322I device uses the CC pins to determine port attach and detach, cable orientation, role detection, and port control for Type-C current mode. The TUSB322I device can be configured as a downstream facing port (DFP), upstream facing port (UFP), or a dual role port (DRP), making the TUSB322I device ideal for any application.

The TUSB322I device alternates configuration as a DFP or UFP according to the Type-C Specifications. The CC logic block monitors the CC1 and CC2 pins for pullup or pulldown resistances to determine when a USB port has been attached, the orientation of the cable, and the role detected. The CC logic detects the Type-C current mode as default, medium, or high depending on the role detected. V<sub>BUS</sub> detection is implemented to determine a successful attach in UFP and DRP modes. The TUSB322I will supply VCONN when an active cable is detected.

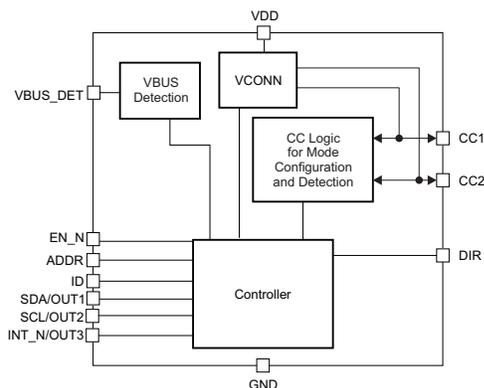
The device operates over a wide supply range and has low-power consumption. The TUSB322I device is available in industrial temperature ranges.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TUSB322I	X2QFN (12)	1.60 mm x 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Simplified Schematic



Copyright © 2016, Texas Instruments Incorporated

### Sample Applications



## Table of Contents

<b>1 Features</b> .....	1	7.5 Programming.....	15
<b>2 Applications</b> .....	1	7.6 Register Maps .....	16
<b>3 Description</b> .....	1	<b>8 Application and Implementation</b> .....	20
<b>4 Revision History</b> .....	2	8.1 Application Information.....	20
<b>5 Pin Configuration and Functions</b> .....	3	8.2 Typical Application .....	20
<b>6 Specifications</b> .....	4	8.3 Initialization Set Up .....	27
6.1 Absolute Maximum Ratings .....	4	<b>9 Power Supply Recommendations</b> .....	27
6.2 ESD Ratings.....	4	<b>10 Layout</b> .....	27
6.3 Recommended Operating Conditions.....	4	10.1 Layout Guidelines .....	27
6.4 Thermal Information .....	4	10.2 Layout Example .....	27
6.5 Electrical Characteristics.....	5	<b>11 Device and Documentation Support</b> .....	28
6.6 Timing Requirements .....	6	11.1 Documentation Support .....	28
6.7 Switching Characteristics .....	7	11.2 Receiving Notification of Documentation Updates	28
<b>7 Detailed Description</b> .....	8	11.3 Community Resources.....	28
7.1 Overview .....	8	11.4 Trademarks .....	28
7.2 Functional Block Diagram .....	8	11.5 Electrostatic Discharge Caution.....	28
7.3 Feature Description.....	8	11.6 Glossary .....	28
7.4 Device Functional Modes.....	13	<b>12 Mechanical, Packaging, and Orderable Information</b> .....	28

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (September 2016) to Revision C	Page
• Changed $R_{V_{BUS}}$ values From: MIN = 891, TYP = 900, MAX = 909 K $\Omega$ To: MIN = 855, TYP = 887, MAX = 920 K $\Omega$ .....	6

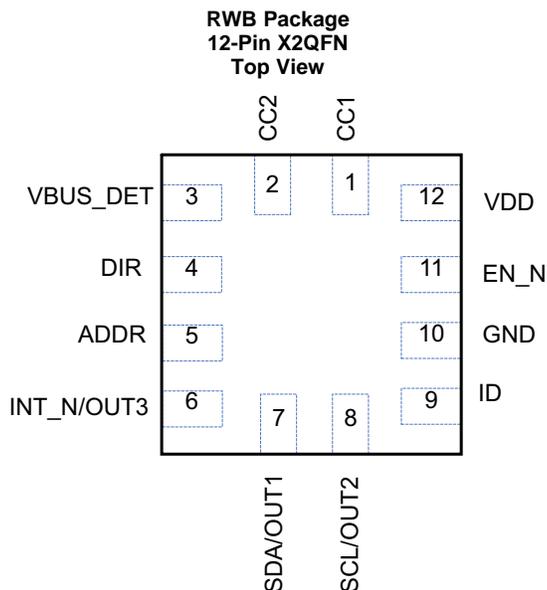
  

Changes from Revision A (May 2016) to Revision B	Page
• Changed pins CC1 and CC2 values From: MIN = -0.3 MAX = $V_{DD} + 0.3$ To: MIN -0.3 MAX = 6 in the <a href="#">Absolute Maximum Ratings</a> .....	4

Changes from Original (October 2015) to Revision A	Page
• Added Shutdown current consumption to <a href="#">Electrical Characteristics</a> table. ....	5

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
CC1	1	I/O	Type-C configuration channel signal 1
CC2	2	I/O	Type-C configuration channel signal 2
VBUS_DET	3	I	5-V to 28-V $V_{BUS}$ input voltage. $V_{BUS}$ detection determines UFP attachment. One 900-k $\Omega$ external resistor required between system $V_{BUS}$ and VBUS_DET pin.
DIR	4	O	DIR of plug. The open drain output indicates the detected plug orientation: Type-C plug position 2 (H); Type-C plug position 1 (L).
ADDR	5	I	Tri-level input pin to indicate I <sup>2</sup> C address or GPIO mode: H - I <sup>2</sup> C is enabled and I <sup>2</sup> C 7-bit address is 0x67. NC - GPIO mode (I <sup>2</sup> C is disabled) L - I <sup>2</sup> C is enabled and I <sup>2</sup> C 7-bit address is 0x47. ADDR pin should be pulled up to $V_{DD}$ if high configuration is desired
INT_N/OUT3	6	O	The INT_N/OUT3 is a dual-function pin. When used as the INT_N, the pin is an open drain output in I <sup>2</sup> C control mode and is an active low interrupt signal for indicating changes in I <sup>2</sup> C registers. When used as OUT3, the pin is in audio accessory detect in GPIO mode: no detection (H), audio accessory connection detected (L).
SDA/OUT1	7	I/O	The SDA/OUT1 is a dual-function pin. When I <sup>2</sup> C is enabled (ADDR pin is high or low), this pin is the I <sup>2</sup> C communication data signal. When in GPIO mode (ADDR pin is NC), this pin is an open drain output for communicating Type-C current mode detect when the TUSB3221 device is in UFP mode: default current mode detected (H); medium or high current mode detected (L).
SCL/OUT2	8	I/O	The SCL/OUT2 is a dual function pin. When I <sup>2</sup> C is enabled (ADDR pin is high or low), this pin is the I <sup>2</sup> C communication clock signal. When in GPIO mode (ADDR pin is NC), this pin is an open drain output for communicating Type-C current mode detect when the TUSB3221 device is in UFP mode: default or medium current mode detected (H); high current mode detected (L).
ID	9	O	Open drain output; asserted low when the CC pins detect device attachment when port is a source (DFP), or dual-role (DRP) acting as source (DFP).
GND	10	G	Ground
EN_N	11	I	EN_N. Active low enable.
$V_{DD}$	12	P	Positive supply voltage

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage	V <sub>DD</sub>	-0.3	6	V
Control pins	ADDR, ID, DIR, INT_N/OUT3, EN_N	-0.3	V <sub>DD</sub> + 0.3	V
	CC1, CC2	-0.3	6	
	SDA/OUT1, SCL/OUT2	-0.3	V <sub>DD</sub> + 0.3	
	VBUS_DET	-0.3	4	
Storage temperature, T <sub>stg</sub>		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods can affect device reliability.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±3000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.  
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V <sub>DD</sub>	Supply voltage	4.5	5	5.5	V
V <sub>BUS</sub>	System V <sub>BUS</sub> voltage	4	5	28	V
VCONTR OL	DC voltage range for control lines: ADDR, ID, DIR, INT_N/OUT3, SDA/OUT1, SCL/OUT2, EN_N, CC1, and CC2.	0		5.5	V
	DC voltage range for VBUSDET	0		4	V
VCONN	Supply for active cable (With V <sub>DD</sub> at 5 V)	4.75		5.5	V
T <sub>A</sub>	Operating free-air temperature	-40	25	85	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TUSB322I	UNIT
		RWB (X2QFN)	
		12 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	169.3	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	68.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	83.4	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	2.2	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	83.4	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and C Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Power Consumption</b>						
$I_{SHUTDOWN\_UFP}$	Leakage current when VDD is supplied but the device is not enabled. (VDD = 5 V, EN_N = H)			0.04		$\mu\text{A}$
$I_{UNATTACHED\_UFP}$	Current consumption in unattached mode when port is unconnected and waiting for connection. (VDD = 5 V, ADDR = NC, MODE_SELECT = 2'b01)			70		$\mu\text{A}$
$I_{ACTIVE\_UFP}$	Current consumption in active mode. (VDD = 5 V, ADDR = NC, MODE_SELECT = 2'b01)			70		$\mu\text{A}$
<b>CC1 and CC2 Pins</b>						
$R_{CC\_DB}$	Pulldown resistor when in dead-battery mode.		4.1	5.1	6.1	$\text{k}\Omega$
$R_{CC\_D}$	Pulldown resistor when in UFP or DRP mode.		4.6	5.1	5.6	$\text{k}\Omega$
$V_{UFP\_CC\_USB}$	Voltage level range for detecting a DFP attach when configured as a UFP and DFP is advertising default current source capability.		0.25		0.61	V
$V_{UFP\_CC\_MED}$	Voltage level range for detecting a DFP attach when configured as a UFP and DFP is advertising medium (1.5 A) current source capability.		0.7		1.16	V
$V_{UFP\_CC\_HIGH}$	Voltage level range for detecting a DFP attach when configured as a UFP and DFP is advertising high (3 A) current source capability.		1.31		2.04	V
$V_{TH\_DFP\_CC\_USB}$	Voltage threshold for detecting a UFP attach when configured as a DFP and advertising default current source capability.		1.51	1.6	1.64	V
$V_{TH\_DFP\_CC\_MED}$	Voltage threshold for detecting a UFP attach when configured as a DFP and advertising medium current (1.5 A) source capability.		1.51	1.6	1.64	V
$V_{TH\_DFP\_CC\_HIGH}$	Voltage threshold for detecting a UFP attach when configured as a DFP and advertising high current (3.0 A) source capability.		2.46	2.6	2.74	V
$V_{TH\_AC\_CC\_USB}$	Voltage threshold for detecting a active cable attach when configured as a DFP and advertising default current source.		0.15	0.2	0.25	V
$V_{TH\_AC\_CC\_MED}$	Voltage threshold for detecting a active cable attach when configured as a DFP and advertising medium current (1.5 A) source.		0.35	0.4	0.45	V
$V_{TH\_AC\_CC\_HIGH}$	Voltage threshold for detecting a active cable attach when configured as a DFP and advertising high current (3.0 A) source.		0.76	0.8	0.84	V
$I_{CC\_DEFAULT\_P}$	Default mode pullup current source when operating in DFP or DRP mode.		64	80	96	$\mu\text{A}$
$I_{CC\_MED\_P}$	Medium (1.5 A) mode pullup current source when operating in DFP or DRP mode.		166	180	194	$\mu\text{A}$
$I_{CC\_HIGH\_P}$	High (3 A) mode pullup current source when operating in DFP or DRP mode. <sup>(1)</sup>		304	330	356	$\mu\text{A}$
<b>Control Pins: EN_N, ADDR, INT/OUT3, DIR, ID</b>						
$V_{IL}$	Low-level control signal input voltage, (EN_N, ADDR)				0.4	V
$V_{IM}$	Mid-level control signal input voltage (ADDR)		$0.28 \times V_{DD}$		$0.56 \times V_{DD}$	V
$V_{IH}$	High-level control signal input voltage (EN_N, ADDR)		$V_{DD} - 0.3$		$V_{DD}$	V
$I_{IH}$	High-level input current		-20		20	$\mu\text{A}$
$I_{IL}$	Low-level input current		-10		10	$\mu\text{A}$
$I_{ID\_LEAKAGE}$	Current leakage on ID pin.	$V_{DD} = 0\text{ V}; ID = 5\text{ V}$			10	$\mu\text{A}$
$R_{EN\_N}$	Internal pull-up resistance for EN_N.			1.1		$\text{M}\Omega$
$R_{pu}$	Internal pullup resistance (ADDR)			588		$\text{k}\Omega$
$R_{pd}$	Internal pulldown resistance (ADDR)			1.1		$\text{M}\Omega$
$V_{OL}$	Low-level signal output voltage (open-drain) (INT_N/OUT3, ID)	$I_{OL} = -1.6\text{ mA}$			0.4	V

 (1)  $V_{DD}$  must be 3.5 V or greater to advertise 3 A current.

## Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R <sub>p_ODext</sub>	External pullup resistor on open drain IOs (INT_N/OUT3, ID)			200		kΩ
R <sub>p_TLext</sub>	Tri-level input external pullup resistor (ADDR)			4.7		kΩ
<b>I<sup>2</sup>C - SDA/OUT1, SCL/OUT2 can operate from 1.8 or 3.3 V (±10%) when ADDR pin is low or high. <sup>(2)</sup></b>						
V <sub>DD_I2C</sub>	Supply range for I <sup>2</sup> C (SDA/OUT1, SCL/OUT2)		1.65	1.8	3.6	V
V <sub>IH</sub>	High-level signal voltage		1.05			V
V <sub>IL</sub>	Low-level signal voltage				0.4	V
V <sub>OL</sub>	Low-level signal output voltage (open drain)	I <sub>OL</sub> = -1.6 mA			0.4	V
<b>VBUS_DET IO Pins (Connected to System V<sub>BUS</sub> signal)</b>						
V <sub>BUS_THR</sub>	V <sub>BUS</sub> threshold range		2.95	3.3	3.8	V
R <sub>VBUS</sub>	External resistor between V <sub>BUS</sub> and VBUS_DET pin		855	887	920	KΩ
R <sub>VBUS_PD</sub>	Internal pulldown resistance for VBUS_DET			95		KΩ
<b>DIR pin (Open Drain IO)</b>						
V <sub>OL</sub>	Low-level signal output voltage	I <sub>OL</sub> = -1.6 mA			0.4	V
<b>VCONN</b>						
R <sub>ON</sub>	On resistance of the VCONN power FET				1.25	Ω
V <sub>TOL</sub>	Voltage tolerance on VCONN power FET				5.5	V
V <sub>PASS</sub>	Voltage to pass through VCONN power FET				5.5	V
I <sub>VCONN</sub>	VCONN current limit; VCONN is disconnected above the value		225	300	375	mA
C <sub>BULK</sub>	Bulk capacitance on VCONN; placed on V <sub>DD</sub> supply		10		200	μF

 (2) When using 3.3 V for I<sup>2</sup>C, customer must ensure V<sub>DD</sub> is above 3.0 V at all times.

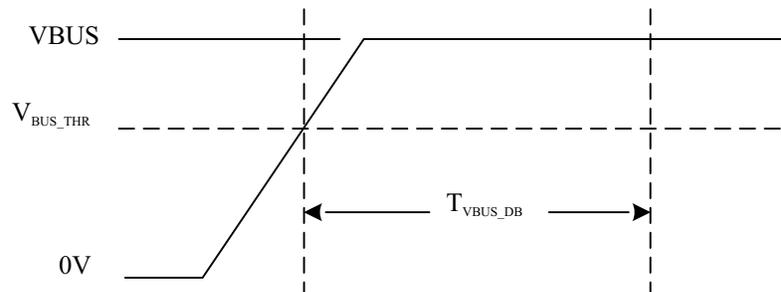
## 6.6 Timing Requirements

		MIN	NOM	MAX	UNIT
<b>I<sup>2</sup>C (SDA, SCL)</b>					
t <sub>SU:DAT</sub>	Data setup time	100			ns
t <sub>HD:DAT</sub>	Data hold time	10			ns
t <sub>SU:STA</sub>	Set-up time, SCL to start condition	0.6			μs
t <sub>HD:STA</sub>	Hold time, (repeated) start condition to SCL	0.6			μs
t <sub>SU:STO</sub>	Set up time for stop condition	0.6			μs
t <sub>VD:DAT</sub>	Data valid time			0.9	μs
t <sub>VD:ACK</sub>	Data valid acknowledge time			0.9	μs
t <sub>BUF</sub>	Bus free time between a stop and start condition	1.3			μs
f <sub>SCL</sub>	SCL clock frequency; I <sup>2</sup> C mode for local I <sup>2</sup> C control			400	kHz
t <sub>r</sub>	Rise time of both SDA and SCL signals			300	ns
t <sub>f</sub>	Fall time of both SDA and SCL signals			300	ns
C <sub>BUS_100KHZ</sub>	Total capacitive load for each bus line when operating at ≤ 100 KHz			400	pF
C <sub>BUS_400KHZ</sub>	Total capacitive load for each bus line when operating at 400 KHz.			100	pF

## 6.7 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{\text{CCCB\_DEFAULT}}$	Power on default of CC1 and CC2 voltage debounce time	DEBOUNCE register = 2'b00		168		ms
$t_{\text{VBUS\_DB}}$	Debounce of VBUS_DET pin after valid $V_{\text{BUS\_THR}}$			2		ms
$t_{\text{DRP\_DUTY\_CYCLE}}$	Power-on default of percentage of time DRP advertises DFP during a $T_{\text{DRP}}$	DRP_DUTY_CYCLE register = 2'b00		30%		
$t_{\text{DRP}}$	The period TUSB3221 in DFP mode completes a DFP to UFP and back advertisement.		50	75	100	ms
$t_{\text{I2C\_EN}}$	Time from EN_N low and $V_{\text{DD}}$ active to I <sup>2</sup> C access available				100	ms
$t_{\text{SOFT\_RESET}}$	Soft reset duration		26	49	95	ms



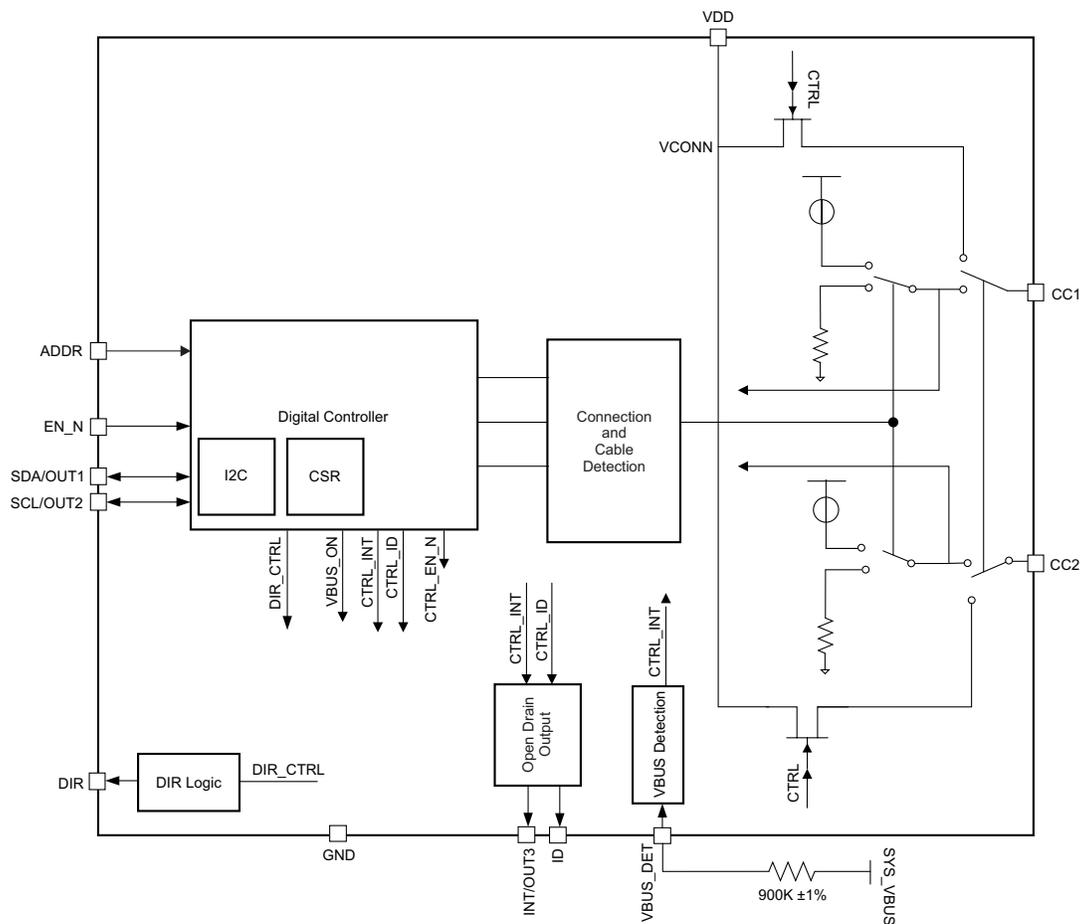
**Figure 1. VBUS Detect and Debounce**

## 7 Detailed Description

### 7.1 Overview

The USB Type-C ecosystem operates around a small form factor connector and cable that is flippable and reversible. Due to the nature of the connector, a scheme is required to determine the connector orientation. Additional schemes are required to determine when a USB port is attached and the acting role of the USB port (DFP, UFP, DRP), as well as to communicate Type-C current capabilities. These schemes are implemented over the CC pins according to the USB Type-C specifications. The TUSB322I device provides Configuration Channel (CC) logic for determining USB port attach and detach, role detection, cable orientation, and Type-C current mode. The TUSB322I device also contains several features such as VCONN sourcing, USB3.1 mux direction control, mode configuration, and low standby current, all of which make the TUSB322I device ideal for source or sinks in USB2.0 or USB3.1 applications.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 Cables, Adapters, and Direct Connect Devices

*Type-C Specification 1.1* defines several cables, plugs, and receptacles to be used to attach ports. The TUSB322I device supports all cables, receptacles, and plugs. The TUSB322I device does not support any USB feature which requires USB Power Delivery communications over CC lines, such as e-marking or alternate mode.

## Feature Description (continued)

### 7.3.1.1 USB Type-C Receptacles and Plugs

Below is list of Type-C receptacles and plugs supported by the TUSB3221 device:

- USB Type-C receptacle for USB2.0 and USB3.1 and full-featured platforms and devices
- USB full-featured Type-C plug
- USB2.0 Type-C plug

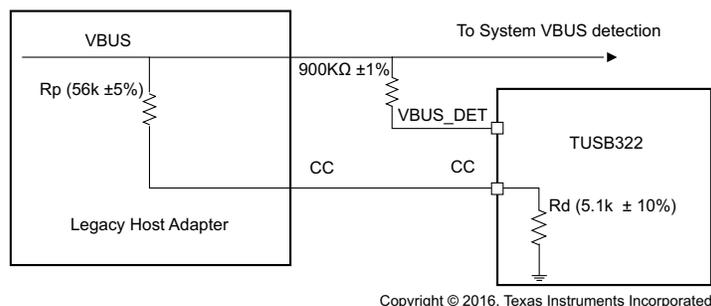
### 7.3.1.2 USB Type-C Cables

Below is a list of Type-C cables types supported by the TUSB3221 device:

- USB full-featured Type-C cable with USB3.1 full-featured plug
- USB2.0 Type-C cable with USB2.0 plug
- Captive cable with either a USB full-featured plug or USB2.0 plug

### 7.3.1.3 Legacy Cables and Adapters

The TUSB3221 device supports legacy cable adapters as defined by the Type-C Specification. The cable adapter must correspond to the mode configuration of the TUSB3221 device.



**Figure 2. Legacy Adapter Implementation Circuit**

### 7.3.1.4 Direct Connect Devices

The TUSB3221 device supports the attaching and detaching of a direct-connect device.

### 7.3.1.5 Audio Adapters

Additionally, the TUSB3221 device supports audio adapters for audio accessory mode, including:

- Passive Audio Adapter
- Charge Through Audio Adapter

## 7.3.2 Port Role Configuration

The TUSB3221 default operation is dual-role port (DRP). The TUSB3221 will always default to DRP operation anytime EN\_N is asserted from high to low or I2C\_SOFT\_RESET bit is set. But the TUSB3221 can be configured as DFP-only or UFP-only through changing the default state of the MODE\_SELECT register. DFP-only and UFP-only mode is not available in GPIO mode. [Table 1](#) lists the supported features in each mode:

**Feature Description (continued)**
**Table 1. Supported Features for the TUSB322I Device by Mode**

SUPPORTED FEATURES	DFP-Only	UFP-Only	DFP
Port attach and detach	Yes	Yes	Yes
Cable orientation (through I <sup>2</sup> C)	Yes	Yes	Yes
Cable orientation through DIR pin	Yes	Yes	Yes
Current advertisement	Yes	—	Yes (DFP)
Current detection	—	Yes	Yes (UFP)
Accessory modes (audio and debug)	Yes	Yes	Yes
Active cable detection	Yes	—	Yes (DFP)
Try.SRC	—	—	Yes (DFP)
Try.SNK	—	—	Yes (UFP)
VCONN	Yes	—	Yes (DFP)
I <sup>2</sup> C / GPIO	Yes	Yes	Yes
Legacy cables	Yes	Yes	Yes
V <sub>BUS</sub> detection	—	Yes	Yes (UFP)

**7.3.2.1 Downstream Facing Port (DFP) - Source**

The TUSB322I device can be configured as a DFP-only device by changing the MODE\_SELECT register default setting. In DFP mode, the TUSB322I device constantly presents Rps on both CC. In DFP mode, the TUSB322I device initially advertises default USB Type-C current. The Type-C current can be adjusted through I<sup>2</sup>C if the system is required to increase the amount advertised. The TUSB322I device adjusts the Rps to match the desired Type-C current advertisement. As a DFP, the TUSB322I monitors the voltage level on CC pins looking for the Rd termination of a UFP. When a UFP is detected and TUSB322I is in the Attached.SRC state, the TUSB322I will supply VCONN on the CC pin that has Ra.

The following list describes the steps for enabling DFP-only.

1. Write a 1'b1 to DISABLE\_TERM register (address 0x0A bit 0)
2. Write a 2'b10 to MODE\_SELECT register (address 0x0A bits 5:4)
3. Write a 1'b0 to DISABLE\_TERM register (address 0x0A bit 0)

When configured as a DFP, the TUSB322I can operate with older USB Type-C 1.0 devices except for a USB Type-C 1.0 DRP device. The TUSB322I cannot operate with a USB Type-C 1.0 DRP device. The limitation is a result of a backwards compatibility problem between USB Type-C 1.1 DFP and a USB Type-C 1.0 DRP.

**7.3.2.2 Upstream Facing Port (UFP) - Sink**

The TUSB322I device can be configured as a UFP-only by changing the MODE\_SELECT register default setting. In UFP mode, the TUSB322I device constantly presents pulldown resistors (Rd) on both CC pins. The TUSB322I device monitors the CC pins for the voltage level corresponding to the Type-C mode current advertisement by the connected DFP. The TUSB322I device debounces the CC pins and wait for V<sub>BUS</sub> detection before successfully attaching. As a UFP, the TUSB322I device detects and communicates the advertised current level of the DFP to the system through the I<sup>2</sup>C CURRENT\_MODE\_DETECT register once in the Attached.SNK state.

Steps for enabling UFP-only:

1. Write a 1'b1 to DISABLE\_TERM register (address 0x0A bit 0).
2. Write a 2'b01 to MODE\_SELECT register (address 0x0A bits 5:4)
3. Write a 1'b0 to DISABLE\_TERM register (address 0x0A bit 0).

### 7.3.2.3 Dual Role Port (DRP)

The TUSB3221 default operation is a dual-role port controller. As a DRP, the TUSB3221 can operate as a UFP (sink) or a DFP (source). In DFP mode, the TUSB3221 toggles between presenting as a DFP (Rp on both CC pins) and presenting as a UFP (Rd on both CC pins).

When presenting as a DFP, the TUSB3221 monitors the voltage level on the CC pins looking for the Rd termination of a UFP. When a UFP is detected and TUSB3221 is in the Attached.SRC state, the TUSB3221 will pull the ID pin low to indicate to the system the port is attached to a sink (UFP). Additionally, when a UFP is detected, the TUSB3221 will supply VCONN on the unconnected CC pin if Ra is also detected. In DFP mode, the TUSB3221 will initially advertise default USB Type-C current. The Type-C Current can be adjusted through I2C if the system wishes to increase the amount advertised. TUSB3221 will adjust the Rps to match the desired Type-C Current advertisement. In GPIO mode, the TUSB3221 will only advertise default Type C current.

When presenting as a UFP, the TUSB3221 monitors the CC pins for the voltage level corresponding to the Type-C mode current advertisement by the connected DFP. The TUSB3221 will debounce the CC pins and wait for VBUS detection before successfully attaching. As a UFP, the TUSB3221 will detect and communicate the DFP's advertised current level to the system through the OUT1 and OUT2 GPIOs (if in GPIO mode) or through the I2C CURRENT\_MODE\_DETECT register once in the Attached.SNK state.

The TUSB3221 supports two optional Type-C DRP features called Try.SRC and Try.SNK. Products supporting dual-role functionality can have a requirement to be a source (DFP) or a sink (UFP) when connected to another dual-role capable product. For example, a dual-role capable notebook can be used as a source when connected to a tablet, or a cell phone could be a sink when connected to a notebook or tablet. When standard DRP products (products which don't support either Try.SRC or Try.SNK) are connected together, the role (UFP or DFP) outcome is not predetermined. These two optional DRP features provide a means for dual-role capable products to connect to another dual-role capable product in the role desired. Try.SRC and Try.SNK are only available when TUSB3221 is configured in I2C mode. When operating in GPIO mode, the TUSB3221 will always operate as a standard DRP.

The Try.SRC feature of the TUSB3221 device provides a means for a DRP product to connect as a DFP when connected to another DRP product that doesn't implement Try.SRC. When two products which implement Try.SRC are connected together, the role outcome of either UFP or DFP is the same as a standard DRP. Try.SRC is enabled by changing I2C register SOURCE\_PREF to 2'b11. Once the register is changed to 2'b11, the TUSB3221 will always attempt to connect as a DFP when attached to another DRP capable device.

### 7.3.3 Type-C Current Mode

When a valid cable detection and attach have been completed, the DFP has the option to advertise the level of Type-C current a UFP can sink. The default current advertisement for the TUSB3221 device is 500 mA (for USB2.0) or 900 mA (for USB3.1). If a higher level of current is available, the I<sup>2</sup>C registers can be written to provide medium current at 1.5 A or high current at 3 A. When the CURRENT\_MODE\_ADVERTISE register has been written to advertise higher than default current, the DFP adjusts the Rps for the specified current level. If a DFP advertises 3 A, it ensures that the V<sub>DD</sub> of the TUSB3221 device is 3.5 V or greater. [Table 2](#) lists the Type-C current advertisements in GPIO and I<sup>2</sup>C modes.

**Table 2. Type-C Current Advertisement for GPIO and I<sup>2</sup>C Modes**

TYPE-C CURRENT		GPIO MODE (ADDR PIN IN NC)		I <sup>2</sup> C MODE (ADDR PIN H, L)	
		UFP IN DRP MODE	DFP IN DRP MODE	UFP	DFP
Default	500 mA (USB2.0) 900 mA (USB3.1)	Current mode detected and output through OUT1 / OUT2	Only advertisement	Current mode detected and read through I <sup>2</sup> C register	I <sup>2</sup> C register default is 500 or 900 mA
Medium - 1.5 A	N/A		Advertisement selected through writing I <sup>2</sup> C register		
High - 3 A					

### 7.3.4 Accessory Support

The TUSB3221 device supports audio and debug accessories in UFP, DFP mode and DRP mode. Audio and debug accessory support is provided through reading of I<sup>2</sup>C registers. Audio accessory is also supported through GPIO mode with INT\_N/OUT3 pin (audio accessory is detected when INT\_N/OUT3 pin is low).

### 7.3.4.1 Audio Accessory

Audio accessory mode is supported through two types of adapters. First, the passive audio adapter can be used to convert the Type-C connector into an audio port. To effectively detect the passive audio adapter, the TUSB322I device must detect a resistance that is less than  $R_a$  on both of the CC pins.

Secondly, a charge through audio adapter can be used. The primary difference between a passive and charge through adapter is that the charge through adapter supplies 500 mA of current over  $V_{BUS}$ . The charge through adapter contains a receptacle and a plug. The plug acts as a DFP and supplies  $V_{BUS}$  when the plug detects a connection.

When the TUSB322I device is configured in GPIO mode, OUT3 pin determines if an audio accessory is connected. When an audio accessory is detected, the OUT3 pin is pulled low.

### 7.3.4.2 Debug Accessory

Debug is an additional state supported by USB Type-C. The specification does not define a specific user scenario for this state, but the end user could use debug accessory mode to enter a test state for production specific to the application. Charge through debug accessory is not supported by TUSB322I when in DRP or UFP mode. The TUSB322I when configured as a DFP-only or as a DRP acting as a DFP will detect a debug accessory which presents  $R_d$  on both CC1 and CC2 pins. The TUSB322I will set ACCESSORY\_CONNECTED register to 3'b110 to indicate a UFP debug accessory. The TUSB322I when configured as a UFP-only or as a DRP acting as a UFP will detect a debug accessory which presents  $R_p$  on both CC1 and CC2 pins. The TUSB322I will set ACCESSORY\_CONNECTED register to 3b'111 to indicate a DFP debug accessory.

### 7.3.5 I<sup>2</sup>C and GPIO Control

The TUSB322I device can be configured for I<sup>2</sup>C communication or GPIO outputs using the ADDR pin. The ADDR pin is a tri-level control pin. When the ADDR pin is left floating (NC), the TUSB322I device is in GPIO output mode. When the ADDR pin is pulled high or pulled low, the TUSB322I device is in I<sup>2</sup>C mode.

All outputs for the TUSB322I device are open drain configuration.

The OUT1 and OUT2 pins are used to output the Type-C current mode when in GPIO mode. Additionally, the OUT3 pin is used to communicate the audio accessory mode in GPIO mode. [Table 3](#) lists the output pin settings. See for more information on the pins and their uses.

**Table 3. Simplified Operation for OUT1 and OUT2**

OUT1	OUT2	DESCRIPTION
H	H	Default current in unattached state
H	L	Default current in attached state
L	H	Medium current (1.5 A) in attached state
L	L	High current (3.0 A) in attached state

When operating in I<sup>2</sup>C mode, the TUSB322I device uses the SCL and SDA lines for clock and data and the INT\_N pin to communicate a change in I<sup>2</sup>C registers, or an interrupt, to the system. The INT\_N pin is pulled low when the TUSB322I device updates the registers with new information. The INT\_N pin is open drain. The INTERRUPT\_STATUS register will be set when the INT\_N pin is pulled low. To clear the INTERRUPT\_STATUS register, the end user writes to I<sup>2</sup>C.

When operating in GPIO mode, the OUT3 pin is used in place of the INT\_N pin to determine if an audio accessory is detected and attached. The OUT3 pin is pulled low when an audio accessory is detected.

#### NOTE

When using the 3.3-V supply for I<sup>2</sup>C, the end user must ensure that the  $V_{DD}$  is 3 V and above. Otherwise the I<sup>2</sup>C can back power the device.

### 7.3.6 $V_{BUS}$ Detection

The TUSB322I device supports  $V_{BUS}$  detection according to the Type-C Specification.  $V_{BUS}$  detection is used to determine the attachment and detachment of a UFP and to determine the entering and exiting of accessory modes.  $V_{BUS}$  detection is also used to successfully resolve the role in DRP mode.

The system  $V_{BUS}$  voltage must be routed through a 900-k $\Omega$  resistor to the VBUS\_DET pin on the TUSB322I device.

### 7.3.7 Cable Orientation and External MUX Control

The TUSB322I device has the ability to control an external/discrete MUX using the DIR pin. The TUSB322I detects the cable orientation by monitoring the voltage on the CC pins. When a voltage level within the proper threshold is detected on CC1, the DIR pin is pulled low. When a voltage level within the proper threshold is detected on CC2, the DIR is pulled high. The DIR pin is an open drain output. The I<sup>2</sup>C communicates the cable orientation status for the TUSB322I device.

### 7.3.8 VCONN Support for Active Cables

The TUSB322I device supplies VCONN to active cables when configured in DFP mode or in DRP acting as a DFP mode. VCONN is provided only when the unconnected CC pin is terminated to a resistance,  $R_a$ , and after a UFP is detected and the Attached.SRC state is entered. When in DFP mode or in DRP acting as a DFP mode, a 5-V source must be connected to the VDD pin of the TUSB322I device after Attached.SRC. VCONN is supplied from VDD through a low resistance power FET out to the unconnected CC pin. VCONN is removed when a detach event is detected and the active cable is removed.

## 7.4 Device Functional Modes

The TUSB322I device has four functional modes. [Table 4](#) lists these modes:

**Table 4. USB Type-C States According to TUSB322I Functional Modes**

MODES	GENERAL BEHAVIOR	MODE	STATES <sup>(1)</sup>
Unattached	USB port unattached. ID, PORT operational. I <sup>2</sup> C on.	UFP-Only	Unattached.SNK
			AttachWait.SNK
		DRP	Toggle Unattached.SNK → Unattached.SRC
			AttachedWait.SRC or AttachedWait.SNK
		DFP-Only	Unattached.SRC
			AttachWait.SRC
Active	USB port attached. All GPIOs operational. I <sup>2</sup> C on.	UFP-Only	Attached.SNK
			Audio Accessory
			Debug Accessory
			Attached.SNK
		DRP	Attached.SRC
			Audio accessory
			Debug accessory
			Attached.SRC
		DFP-Only	Audio accessory
			Debug accessory
			Attached.SRC
			Debug accessory
Dead battery	No operation. $V_{DD}$ not available.	DRP	Default device state to UFP/SNK with Rd.
Shutdown	No operation. $V_{DD}$ available and EN_N pin high	DRP	Default device state to UFP/SNK with Rd.

(1) Required; not in sequential order.

### 7.4.1 Unattached Mode

Unattached mode is the primary mode of operation for the TUSB322I device, because a USB port can be unattached for a lengthy period of time. In unattached mode,  $V_{DD}$  is available, and all IOs and I<sup>2</sup>C are operational. After the TUSB322I device is powered up, the part enters unattached mode until a successful attach has been determined. Initially, right after power up, the TUSB322I device comes up as an Unattached.SNK. The TUSB322I device toggles between the UFP and the DFP if configured as a DRP.

### 7.4.2 Active Mode

Active mode is defined as the port being attached. In active mode, all GPIOs are operational, and I<sup>2</sup>C is read / write (R/W). When in active mode, the TUSB322I device communicates to the AP that the USB port is attached. This communication happens through the ID pin if TUSB322I is configured as a DFP or DRP connect as source. If TUSB322I is configured as a UFP or a DRP connected as a sink, the OUT1/OUT2 and INT\_N/OUT3 pins are used. The TUSB322I device exits active mode under the following conditions:

- Cable unplug
- V<sub>BUS</sub> removal if attached as a UFP
- Dead battery; system battery or supply is removed
- EN\_N is floated or pulled high.

### 7.4.3 Shutdown Mode

Shutdown mode for TUSB322I is defined as follows:

- Supply voltage available and EN\_N pin is high or floating.
- EN\_N pin has internal pullup resistor
- The TUSB322I device is off, but still maintains the Rd on the CC pins.

### 7.4.4 Dead Battery Mode

During dead battery mode, V<sub>DD</sub> is not available. CC pins always default to pulldown resistors in dead battery mode. Dead battery mode means:

- TUSB322I in UFP with 5.1 kΩ ± 20% Rd; cable connected and providing charge
- TUSB322I in UFP with 5.1 kΩ ± 20% Rd; nothing connected (application could be off or have a discharged battery)

---

#### NOTE

When V<sub>DD</sub> is off, the TUSB322I non-failsafe pins (DIR, VBUS\_DET, ADDR, OUT[3:1] pins) could back-drive the TUSB322I device if not handled properly. When necessary to pull these pins up, TI recommends pulling up DIR, ADDR, and INT\_N/OUT3 to the device's V<sub>DD</sub> supply. The VBUS\_DET must be pulled up to V<sub>BUS</sub> through a 900-kΩ resistor.

---

## 7.5 Programming

For further programmability, the TUSB3221 device can be controlled using I<sup>2</sup>C. The TUSB3221 device local I<sup>2</sup>C interface is available for reading/writing after T<sub>I<sup>2</sup>C\_EN</sub> when the device is powered up. The SCL and SDA terminals are used for I<sup>2</sup>C clock and I<sup>2</sup>C data respectively. If I<sup>2</sup>C is the preferred method of control, the ADDR pin must be set accordingly.

**Table 5. TUSB3221 I<sup>2</sup>C Addresses**

TUSB3221 I <sup>2</sup> C Target Address								
ADDR pin	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (W/R)
H	1	1	0	0	1	1	1	0/1
L	1	0	0	0	1	1	1	0/1

The following procedure should be followed to write to TUSB3221 I<sup>2</sup>C registers:

1. The master initiates a write operation by generating a start condition (S), followed by the TUSB3221 7-bit address and a zero-value R/W bit to indicate a write cycle
2. The TUSB3221 device acknowledges the address cycle
3. The master presents the sub-address (I<sup>2</sup>C register within the TUSB3221 device) to be written, consisting of one byte of data, MSB-first
4. The TUSB3221 device acknowledges the sub-address cycle
5. The master presents the first byte of data to be written to the I<sup>2</sup>C register
6. The TUSB3221 device acknowledges the byte transfer
7. The master can continue presenting additional bytes of data to be written, with each byte transfer completing with an acknowledge from the TUSB3221 device
8. The master terminates the write operation by generating a stop condition (P)

The following procedure should be followed to read the TUSB3221 I<sup>2</sup>C registers:

1. The master initiates a read operation by generating a start condition (S), followed by the TUSB3221 7-bit address and a one-value R/W bit to indicate a read cycle
2. The TUSB3221 device acknowledges the address cycle
3. The TUSB3221 device transmits the contents of the memory registers MSB-first starting at register 00h or last read sub-address+1. If a write to the T I<sup>2</sup>C register occurred prior to the read, then the TUSB3221 device starts at the sub-address specified in the write.
4. The TUSB3221 device waits for either an acknowledge (ACK) or a not-acknowledge (NACK) from the master after each byte transfer; the I<sup>2</sup>C master acknowledges reception of each data byte transfer
5. If an ACK is received, the TUSB3221 device transmits the next byte of data
6. The master terminates the read operation by generating a stop condition (P)

The following procedure should be followed for setting a starting sub-address for I<sup>2</sup>C reads:

1. The master initiates a write operation by generating a start condition (S), followed by the TUSB3221 7-bit address and a zero-value R/W bit to indicate a read cycle
2. The TUSB3221 device acknowledges the address cycle
3. The master presents the sub-address (I<sup>2</sup>C register within the TUSB3221 device) to be read, consisting of one byte of data, MSB-first
4. The TUSB3221 device acknowledges the sub-address cycle
5. The master terminates the read operation by generating a stop condition (P)

### NOTE

If no sub-addressing is included for the read procedure, then the reads start at register offset 00h and continue byte-by-byte through the registers until the I<sup>2</sup>C master terminates the read operation. If a I<sup>2</sup>C address write occurred prior to the read, then the reads start at the sub-address specified by the address write.

## 7.6 Register Maps

### 7.6.1 CSR Registers

**Table 6. CSR Registers**

Offset	Reset	Register Name	Section
0x07 through 0x00	[0x00, 0x54, 0x55, 0x53, 0x42, 0x33, 0x32, 0x32]	Device Identification	<a href="#">Device Identification Register</a>
0x08	0x00	Connection Status	<a href="#">Connection Status Register</a>
0x09	0x20	Connection Status and Control	<a href="#">Connection Status and Control Register</a>
0x0A	0x00	General Control	<a href="#">General Control Register</a>
0xA0	0x02	Device Revision	<a href="#">Device Revision Register</a>

#### 7.6.1.1 Device Identification Register (offset = 0x07 through 0x00) [reset = 0x00, 0x54, 0x55, 0x53, 0x42, 0x33, 0x32, 0x32]

**Figure 3. Device Identification Register**

7	6	5	4	3	2	1	0
DEVICE_ID							
R-0							

LEGEND: R = Read only; -n = value after reset

**Table 7. Device Identification Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	DEVICE_ID	R		For the TUSB322I device these fields return a string of ASCII characters returning TUSB322I Addresses 0x07 - 0x00 = {0x00, 0x54, 0x55, 0x53, 0x42, 0x33, 0x32, 0x32}

#### 7.6.1.2 Connection Status Register (offset = 0x08) [reset = 0x00]

**Figure 4. Connection Status Register**

7	6	5	4	3	2	1	0
CURRENT_MODE_ADVERTISE		CURRENT_MODE_DETECT		ACCESSORY_CONNECTED			ACTIVE_CABLE_DETECTION
RW		RU		RU			RU

LEGEND: R/W = Read/Write; R/U = Read/Update

**Table 8. Connection Status Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	CURRENT_MODE_ADVERTISE	R	2'b00	These bits are programmed by the application to raise the current advertisement from default. 00 – Default (500 mA / 900 mA) initial value at startup 01 – Mid (1.5 A) 10 – High (3 A) 11 – Reserved
5-4	CURRENT_MODE_DETECT	RU	2'b00	These bits are set when a UFP determines the Type-C Current mode. 00 – Default (value at start up) 01 – Medium 10 – Charge through accessory – 500 mA 11 – High

**Table 8. Connection Status Register Field Descriptions (continued)**

Bit	Field	Type	Reset	Description
3-1	ACCESSORY_CONNECTED	RU	2'b00	<p>These bits are read by the application to determine if an accessory was attached.</p> <p>000 – No accessory attached (default)  001 – Reserved  010 – Reserved  011 – Reserved  100 – Audio accessory  101 – Audio charged thru accessory  110 – Debug accessory when TUSB3221 is connected as a DFP.  111 – Debug accessory when TUSB3221 is connected as a UFP.</p>
0	ACTIVE_CABLE_DETECTION	RU	1'b0	<p>This flag indicates that an active cable has been plugged into the Type-C connector. When this field is set, an active cable is detected.</p>

**7.6.1.3 Connection Status and Control Register (offset = 0x09) [reset = 0x20]**
**Figure 5. Connection Status and Control Register**

7	6	5	4	3	2	1	0
ATTACHED_STATE	CABLE_DIR	INTERRUPT_S TATUS	VCONN_FAUL T	DRP_DUTY_CYCLE	DISABLE_UFP _ACCESSORY		
RU	RU	RCU	RCU	RW	RW		

LEGEND: R/W = Read/Write; R/U = Read/Update; R/C/U = Read/Clear/Update

**Table 9. Connection Status and Control Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	ATTACHED_STATE	RU	2'b00	<p>This is an additional method to communicate attach other than the ID pin. These bits can be read by the application to determine what was attached.</p> <p>00 – Not attached (default)  01 – Attached.SRC (DFP)  10 – Attached.SNK (UFP)  11 – Attached to an accessory</p>
5	CABLE_DIR	RU	1'b1	<p>Cable orientation. The application can read these bits for cable orientation information.</p> <p>0 – CC1  1 – CC2 (default)</p>
4	INTERRUPT_STATUS	RCU	1'b0	<p>The INT pin is pulled low whenever a CSR changes. When a CSR change has occurred this bit should be held at 1 until the application clears it.</p> <p>0 – Clear  1 – Interrupt (When INT_N is pulled low, this bit will be 1. This bit is 1 whenever any CSR are changed)</p>
3	VCONN_FAULT	RCU	1'b0	<p>VCONN_FAULT Bit is set whenever a VCONN over-current limit is triggered.</p> <p>0 - No fault. (default)  1 - Interrupt (INT_N is asserted low)</p>

**Table 9. Connection Status and Control Register Field Descriptions (continued)**

Bit	Field	Type	Reset	Description
2-1	DRP_DUTY_CYCLE	RW	2'b00	Percentage of time that a DRP advertises DFP during tDRP 00 – 30% (default) 01 – 40% 10 – 50% 11 – 60%
0	DISABLE_UFP_ACCESSORY	RW	1'b0	Setting this field will disable UFP accessory support. 0 – UFP accessory support enabled (Default) 1 – UFP accessory support disabled

**7.6.1.4 General Control Register (offset = 0x0A) [reset = 0x00]**
**Figure 6. General Control Register**

7	6	5	4	3	2	1	0
DEBOUNCE		MODE_SELECT		I <sup>2</sup> C_SOFT_RE SET	SOURCE_PREF		DISABLE_TER M
RW		RW		RSU	RW		RW

LEGEND: R/W = Read/Write; R/S/U = Read/Set/Update

**Table 10. General Control Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	DEBOUNCE	RW	2'b00	The nominal amount of time the TUSB322I device debounces the voltages on the CC pins. 00 – 168ms (default) 01 – 118ms 10 – 134ms 11 – 152ms
5-4	MODE_SELECT	RW	2'b00	This register can be written to set the TUSB322I device mode operation. The ADDR pin must be set to I <sup>2</sup> C mode. 00 – DRP mode (start from unattached.SNK) (default) 01 – UFP mode (unattached.SNK) 10 – DFP mode(unattached.SRC) 11 – DRP mode(start from unattached.SNK)
3	I <sup>2</sup> C_SOFT_RESET	RSU	1'b0	This register resets the digital logic. The bit is self-clearing. A write of 1 starts the reset. The following registers can be affected after setting this bit: CURRENT_MODE_DETECT ACTIVE_CABLE_DETECTION ACCESSORY_CONNECTED ATTACHED_STATE CABLE_DIR
2-1	SOURCE_PREF	RW	2'b00	This field controls the TUSB322I behavior when configured as a DRP. 00 – Standard DRP (default) 01 – DRP will perform Try.SNK 10 – Reserved 11 – DRP will perform Try.SRC

**Table 10. General Control Register Field Descriptions (continued)**

Bit	Field	Type	Reset	Description
0	DISABLE_TERM	RW	1'b0	This field will disable the termination on CC pins and transition the CC state machine to the disabled state. 0 – Termination enabled according TUSB3221 mode of operation (default) 1 – Termination disabled and state machine held in disable state.

**7.6.1.5 Device Revision Register (offset = 0xA0) [reset = 0x02]**
**Figure 7. Device Revision Register**

7	6	5	4	3	2	1	0
REVISION							
R							

LEGEND: R = Read only

**Table 11. Device Revision Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	REVISION	R	'h02	Revision of TUSB3221. Defaults to 0x02.

## 8 Application and Implementation

---

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

---

### 8.1 Application Information

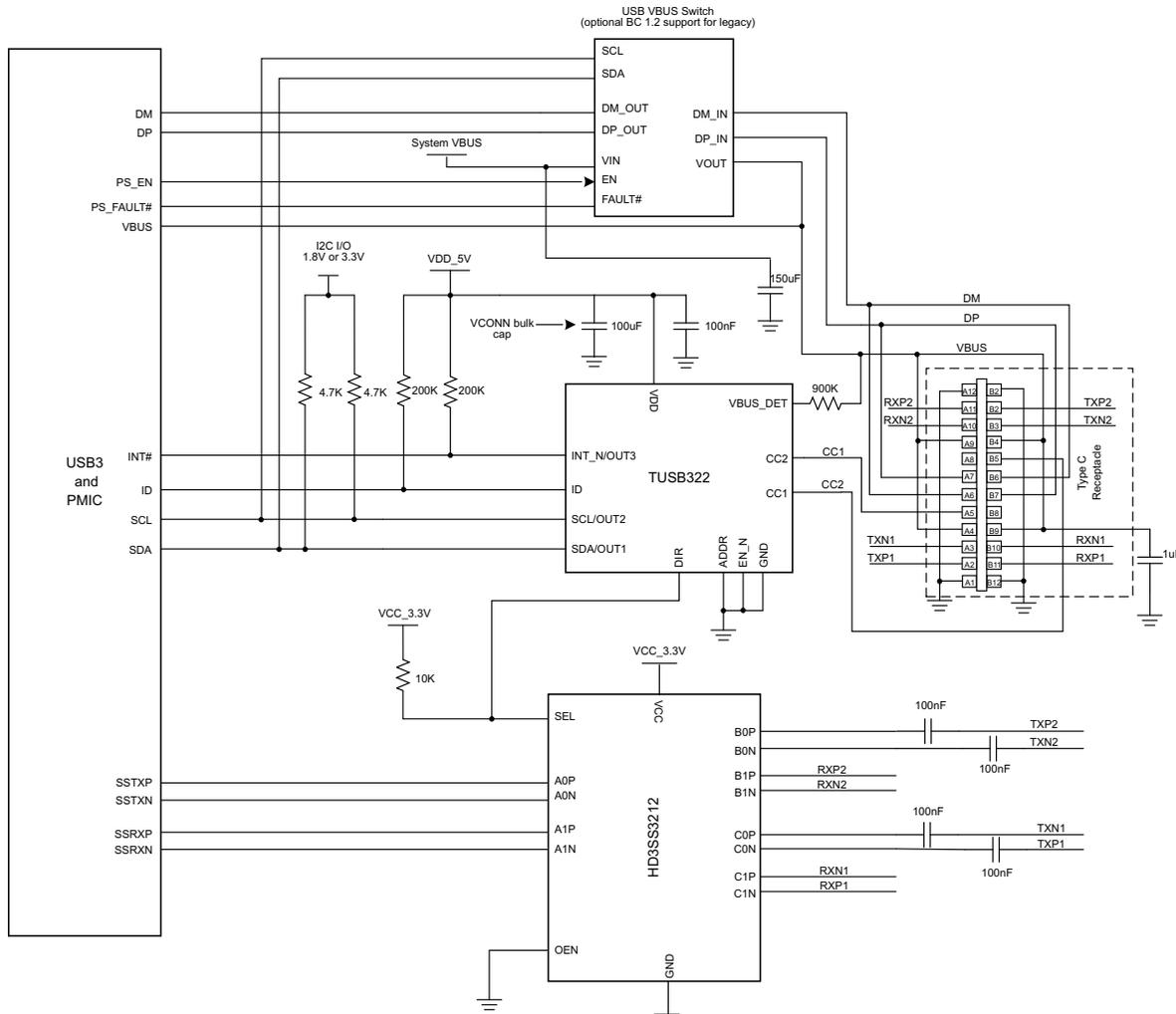
The TUSB322I device is a Type-C configuration channel logic and port controller. The TUSB322I device can detect when a Type-C device is attached, what type of device is attached, the orientation of the cable, and power capabilities (both detection and broadcast). The TUSB322I device can be used in a source application (DFP) or in a sink application (UFP).

### 8.2 Typical Application

## Typical Application (continued)

### 8.2.1 DRP in I<sup>2</sup>C Mode

Figure 8 shows the TUSB3221 device configured as a DRP in I<sup>2</sup>C mode.



Copyright © 2016, Texas Instruments Incorporated

Figure 8. DRP in I<sup>2</sup>C Mode Schematic

#### 8.2.1.1 Design Requirements

For the design example, use the parameters listed in Table 12.

Table 12. Design Requirements for DRP in I<sup>2</sup>C Mode

DESIGN PARAMETER	VALUE
V <sub>DD</sub> (4.5 to 5.5 V)	5 V
Mode (I <sup>2</sup> C or GPIO)	I <sup>2</sup> C ADDR pin must be pulled down or pulled up
I <sup>2</sup> C address (0x67 or 0x47)	0x47 ADDR pin must be pulled low or tied to GND
Type-C port type (UFP, DFP, or DRP)	DRP MODE_SELECT register = 2'b00.
VCONN Support	Yes

### 8.2.1.2 Detailed Design Procedure

The TUSB322I device supports a  $V_{DD}$  in the range of 4.5 V to 5.5 V. In this particular use case, 5 V is connected to the  $V_{DD}$  pin. Because VCONN support is required for a DRP, the 5 V on  $V_{DD}$  meets the USB Type-C VCONN requirement of 4.75 V to 5.5 V. A 100-nF capacitor is placed near  $V_{DD}$ . Also, a 100- $\mu$ F capacitor is used to meet the USB Type-C bulk capacitance requirement of 10  $\mu$ F to 220  $\mu$ F.

The TUSB322I device is placed into I<sup>2</sup>C mode by either pulling the ADDR pin high or low. In this case, the ADDR pin is tied to GND which results in a I<sup>2</sup>C address of 0x47. The SDA and SCL must be pulled up to either 1.8 V or 3.3 V. When pulled up to 3.3 V, the  $V_{DD}$  supply must be at least 3 V to keep from back-driving the I<sup>2</sup>C interface.

The INT\_N/OUT3 pin is used to notify the PMIC when a change in the TUSB322I I<sup>2</sup>C registers occurs. This pin is an open drain output and requires an external pullup resistor. The pin should be pulled up to  $V_{DD}$  using a 200-k $\Omega$  resistor.

The ID pin is used to indicate when a connection has occurred if the TUSB322I device is a DFP while configured for DRP. An OTG USB controller can use this pin to determine when to operate as a USB Host or USB Device. When this pin is driven low, the OTG USB controller functions as a host and then enables  $V_{BUS}$ . The Type-C standard requires that a DFP not enable  $V_{BUS}$  until the  $V_{BUS}$  is in the Attached.SRC state. If the ID pin is not low but  $V_{BUS}$  is detected, then the OTG USB controller functions as a device. The ID pin is open drain output and requires an external pullup resistor. The ID pin should be pulled up to  $V_{DD}$  using a 200-k $\Omega$  resistor.

The DIR pin is used to control the mux for connecting the USB3 SS signals to the appropriate pins on the USB Type-C receptacle. In this particular case, a HD3SS3212 is used as the mux. To minimize crossing in routing the USB3 SS signals to the USB Type C connector, the connection of CC1 and CC2 to the TUSB322I is swapped. When swapping the CC1 and CC2 connection, the CABLE\_DIR register will also be reversed (0 = CC2 and 1 = CC1).

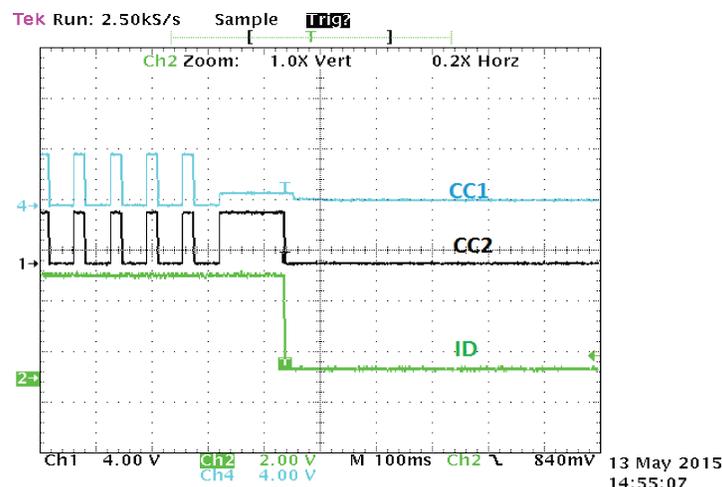
The VBUS\_DET pin must be connected through a 900-k $\Omega$  resistor to  $V_{BUS}$  on the Type-C that is connected. This large resistor is required to protect the TUSB322I device from large  $V_{BUS}$  voltage that is possible in present day systems. This resistor along with internal pulldown keeps the voltage observed by the TUSB322I device in the recommended range.

The USB2 specification requires the bulk capacitance on  $V_{BUS}$  based on UFP or DFP. When operating the TUSB322I device in a DRP mode, it alternates between UFP and DFP. If the TUSB322I device connects as a UFP, the large bulk capacitance must be removed.

**Table 13. USB2 Bulk Capacitance Requirements**

PORT CONFIGURATION	MIN	MAX	UNIT
Downstream facing port (DFP)	120		$\mu$ F
Upstream facing port (UFP)	1	10	$\mu$ F

### 8.2.1.3 Application Curves



**Figure 9. Application Curve for DRP in I<sup>2</sup>C Mode**



### 8.2.2.2 Detailed Design Procedure

The TUSB322I device supports a  $V_{DD}$  in the range of 4.5 V to 5.5 V. In this particular case,  $V_{DD}$  is set to 5 V. A 100-nF capacitor is placed near  $V_{DD}$ . Also, a 100- $\mu$ F capacitor is used to meet the USB Type-C bulk capacitance requirement of 10  $\mu$ F to 220  $\mu$ F.

The TUSB322I device is placed into I<sup>2</sup>C mode by either pulling the ADDR pin high or low. In this particular case, the ADDR pin is tied to GND which results in a I<sup>2</sup>C address of 0x47. The SDA and SCL must be pulled up to either 1.8 V or 3.3 V. When pulled up to 3.3 V, the  $V_{DD}$  supply must be at least 3 V to keep from back-driving the I<sup>2</sup>C interface.

The INT\_N/OUT3 pin is used to notify the PMIC when a change in the TUSB322I I<sup>2</sup>C registers occurs. This pin is an open drain output and requires an external pullup resistor. The pin should be pulled up to  $V_{DD}$  using a 200-k $\Omega$  resistor.

The DIR pin is used to control the mux for connecting the USB3 SS signals to the appropriate pins on the USB Type-C receptacle. In this particular case, a HD3SS3212 is used as the mux. To minimize crossing in routing the USB3 SS signals to the USB Type C connector, the connection of CC1 and CC2 to the TUSB322I is swapped. When swapping the CC1 and CC2 connection, the CABLE\_DIR register will also be reversed (0 = CC2 and 1 = CC1).

The Type-C port mode is determined by the state of the MODE\_SELECT register. When the MODE\_SELECT register is 2'b10, the TUSB322I device is in DFP mode. The TUSB322I will exit the DFP mode if the MODE\_SELECT register is changed, I2C\_SOFT\_RESET is set, or EN\_N pin is transitioned from high to low.

The VBUS\_DET pin must be connected through a 900-k $\Omega$  resistor to  $V_{BUS}$  on the Type-C that is connected. This large resistor is required to protect the TUSB322I device from large  $V_{BUS}$  voltage that is possible in present day systems. This resistor along with internal pulldown keeps the voltage observed by the TUSB322I device in the recommended range.

The USB2 specification requires the bulk capacitance on  $V_{BUS}$  based on UFP or DFP. When operating the TUSB322I device in a DFP mode, a bulk capacitance of at least 120  $\mu$ F is required. In this particular case, a 150- $\mu$ F capacitor was chosen.

### 8.2.2.3 Application Curves

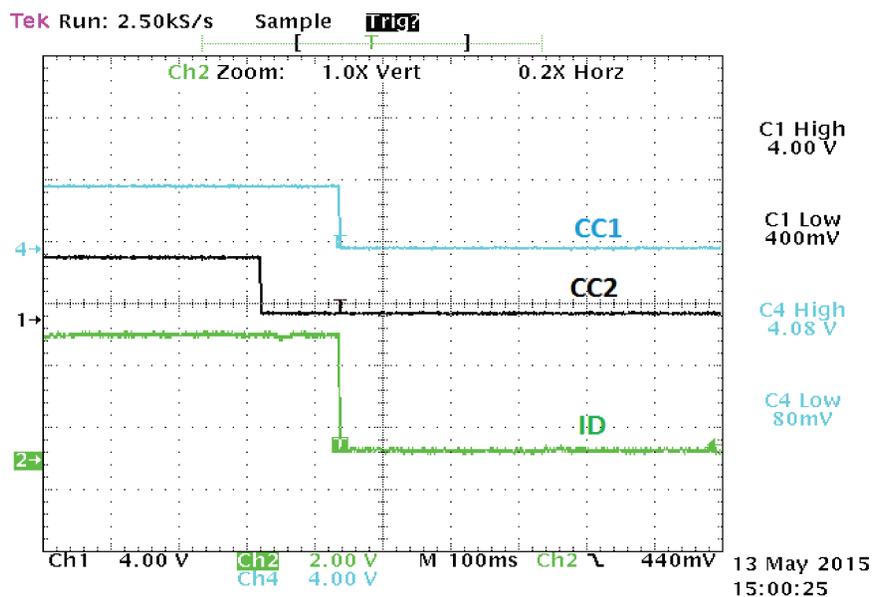
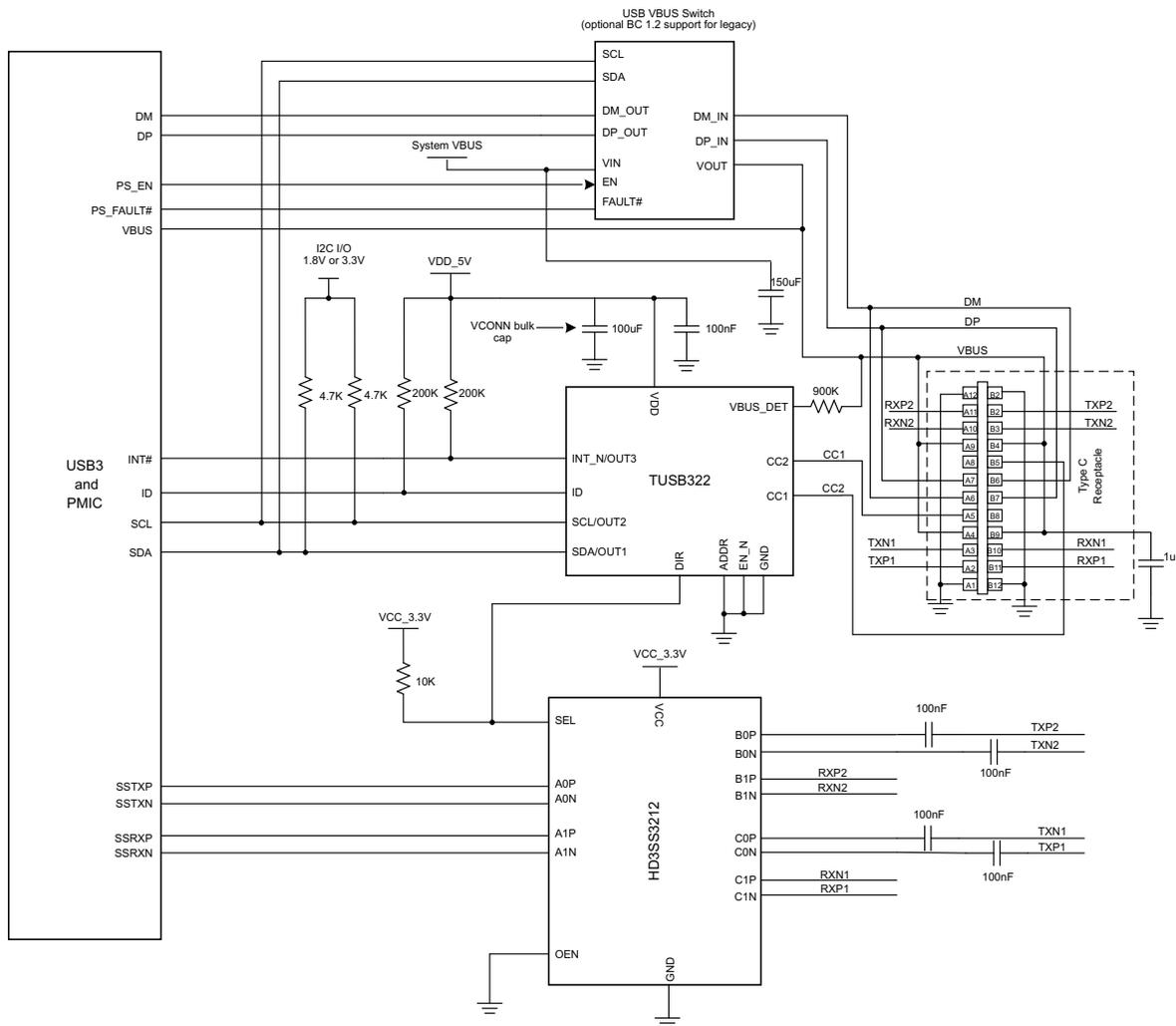


Figure 11. Application Curve for DFP in I<sup>2</sup>C Mode

### 8.2.3 UFP in I<sup>2</sup>C Mode

Figure 12 shows the TUSB3221 device configured as a UFP in I<sup>2</sup>C mode.



Copyright © 2016, Texas Instruments Incorporated

Figure 12. UFP in I<sup>2</sup>C Mode Schematic

#### 8.2.3.1 Design Requirements

For the design example, use the parameters listed in Table 15:

Table 15. Design Requirements for UFP in I<sup>2</sup>C Mode

DESIGN PARAMETER	VALUE
V <sub>DD</sub> (4.5 V to 5.5 V)	5 V
Mode (I <sup>2</sup> C or GPIO)	I <sup>2</sup> C ADDR pin must be pulled down or pulled up
I <sup>2</sup> C address (0x61 or 0x60)	0x47 ADDR pin must be pulled low or tied to GND
Type-C port type (UFP, DFP, or DRP)	UFP MODE_SELECT = 2'b01
VCONN Support	No

### 8.2.3.2 Detailed Design Procedure

The TUSB322I device supports a  $V_{DD}$  in the range of 4.5 V to 5.5 V. In this particular case,  $V_{DD}$  is set to 5 V. A 100-nF capacitor is placed near  $V_{DD}$ .

The TUSB322I device is placed into I<sup>2</sup>C mode by either pulling the ADDR pin high or low. In this case, the ADDR pin is tied to GND which results in a I<sup>2</sup>C address of 0x47. The SDA and SCL must be pulled up to either 1.8 V or 3.3 V. When pulled up to 3.3 V, the  $V_{DD}$  supply must be at least 3 V to keep from back-driving the I<sup>2</sup>C interface.

The INT\_N/OUT3 pin is used to notify the PMIC when a change in the TUSB322I I<sup>2</sup>C registers occurs. This pin is an open drain output and requires an external pullup resistor. The pin should be pulled up to  $V_{DD}$  using a 200-k $\Omega$  resistor.

The DIR pin is used to control the mux for connecting the USB3 SS signals to the appropriate pins on the USB Type-C receptacle. In this particular case, a HD3SS3212 is used as the mux. To minimize crossing in routing the USB3 SS signals to the USB Type C connector, the connection of CC1 and CC2 to the TUSB322I is swapped. When swapping the CC1 and CC2 connection, the CABLE\_DIR register will also be reversed (0 = CC2 and 1 = CC1).

The Type-C port mode is determined by the state of the MODE\_SELECT register. When the MODE\_SELECT register is 2'b01, the TUSB322I device is in UFP mode. The TUSB322I will exit the UFP mode if the MODE\_SELECT register is changed, I2C\_SOFT\_RESET is set, or EN\_N pin is transitioned from high to low.

The VBUS\_DET pin must be connected through a 900-k $\Omega$  resistor to  $V_{BUS}$  on the Type-C that is connected. This large resistor is required to protect the TUSB322I device from large  $V_{BUS}$  voltage that is possible in present day systems. This resistor along with internal pulldown keeps the voltage observed by the TUSB322I device in the recommended range.

The USB2 specification requires the bulk capacitance on  $V_{BUS}$  based on UFP or DFP. When operating the TUSB322I device in a UFP mode, a bulk capacitance between 1  $\mu$ F to 10  $\mu$ F is required. In this particular case, a 1- $\mu$ F capacitor was chosen.

### 8.2.3.3 Application Curves

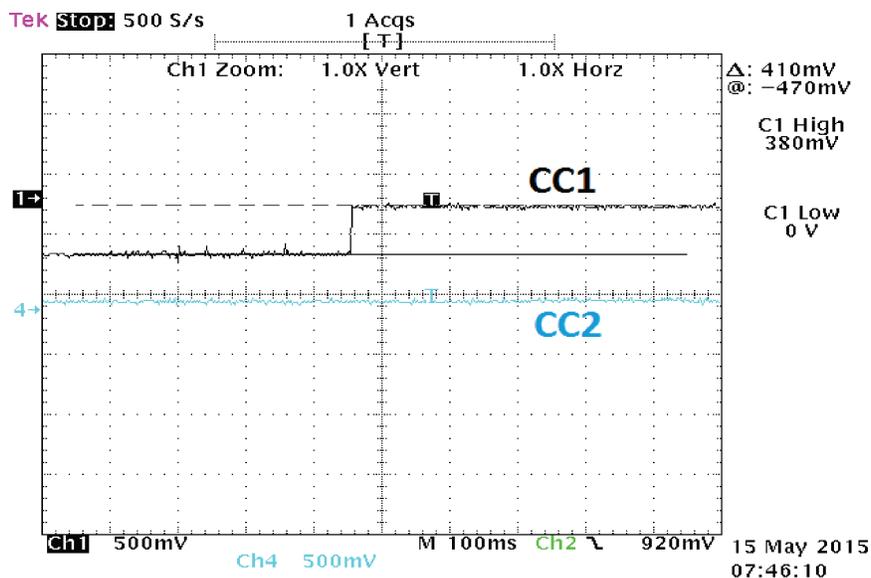


Figure 13. Application Curve for UFP in I<sup>2</sup>C Mode

### 8.3 Initialization Set Up

The general power-up sequence for the TUSB322I device (EN\_N tied to GND) is as follows:

1. System is powered off (device has no  $V_{DD}$ ). The TUSB322I device is configured internally in UFP mode with Rds on CC pins (dead battery).
2.  $V_{DD}$  ramps – POR circuit.
3. I<sup>2</sup>C supply ramps up.
4. The TUSB322I device enters unattached.SNK and functions as a DRP. If DRP is not the desired mode of operation, then software must change MODE\_SELECT register to desired mode (UFP or DFP).
5. The TUSB322I device monitors the CC pins as a DFP and  $V_{BUS}$  for attach as a UFP.
6. The TUSB322I device enters active mode when attach has been successfully detected.

## 9 Power Supply Recommendations

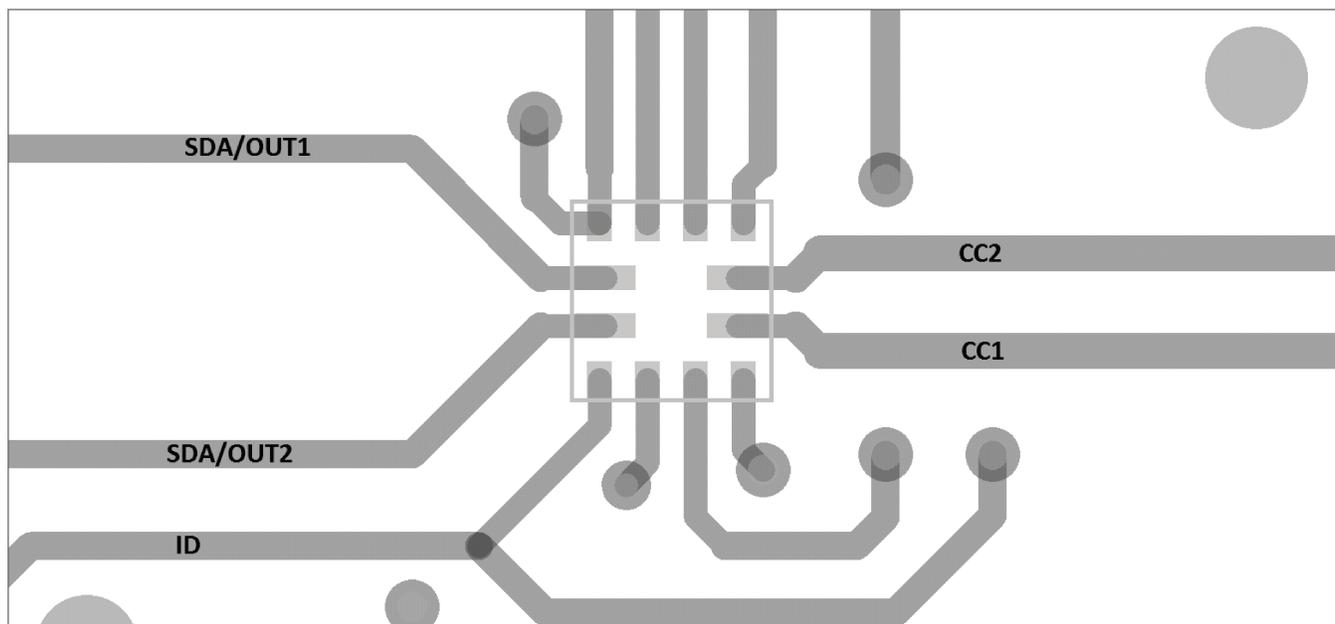
The TUSB322I device has a wide power supply range from 4.5 to 5.5 V. The TUSB322I device can be run off of a system power such as a battery.

## 10 Layout

### 10.1 Layout Guidelines

1. An extra trace (or stub) is created when connecting between more than two points. A trace connecting pin A6 to pin B6 will create a stub because the trace also has to go to the USB Host. Ensure that:
  - A stub created by short on pin A6 (DP) and pin B6 (DP) at Type-C receptacle does not exceed 3.5 mm.
  - A stub created by short on pin A7 (DM) and pin B7 (DM) at Type-C receptacle does not exceed 3.5 mm.
2. A 100-nF capacitor should be placed as close as possible to the TUSB322I  $V_{DD}$  pin.

### 10.2 Layout Example



**Figure 14. TUSB322I Layout**

## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

- *Semiconductor and C Package Thermal Metrics* application report, [SPRA953](#)

### 11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.4 Trademarks

E2E is a trademark of Texas Instruments.

USB Type-C is a trademark of USB Implementers Forum.

All other trademarks are the property of their respective owners.

### 11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TUSB322IRWBR</a>	Active	Production	X2QFN (RWB)   12	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	72
TUSB322IRWBR.A	Active	Production	X2QFN (RWB)   12	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	72
TUSB322IRWBRG4	Active	Production	X2QFN (RWB)   12	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	72
TUSB322IRWBRG4.A	Active	Production	X2QFN (RWB)   12	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	72

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

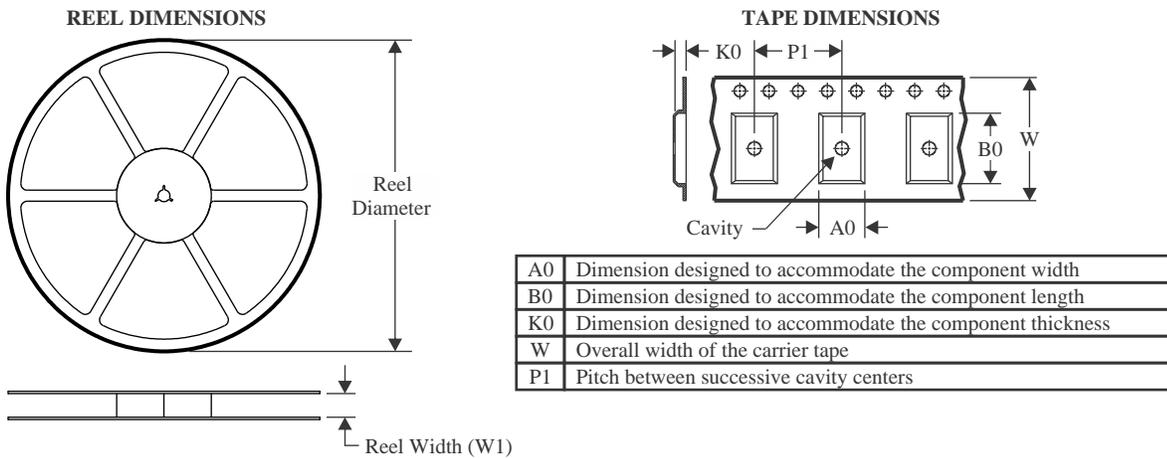
<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

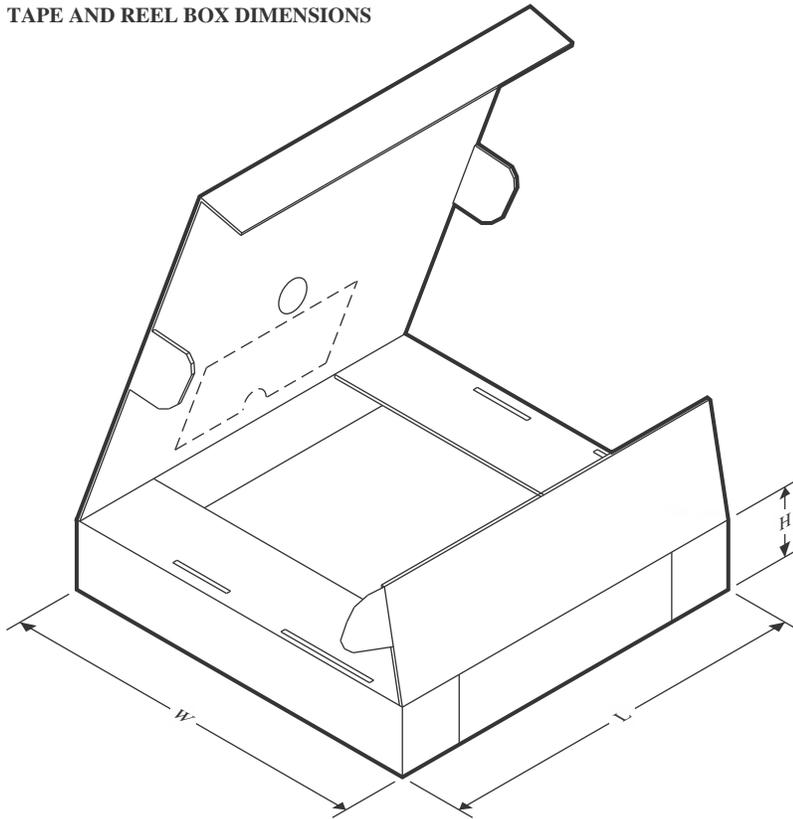
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

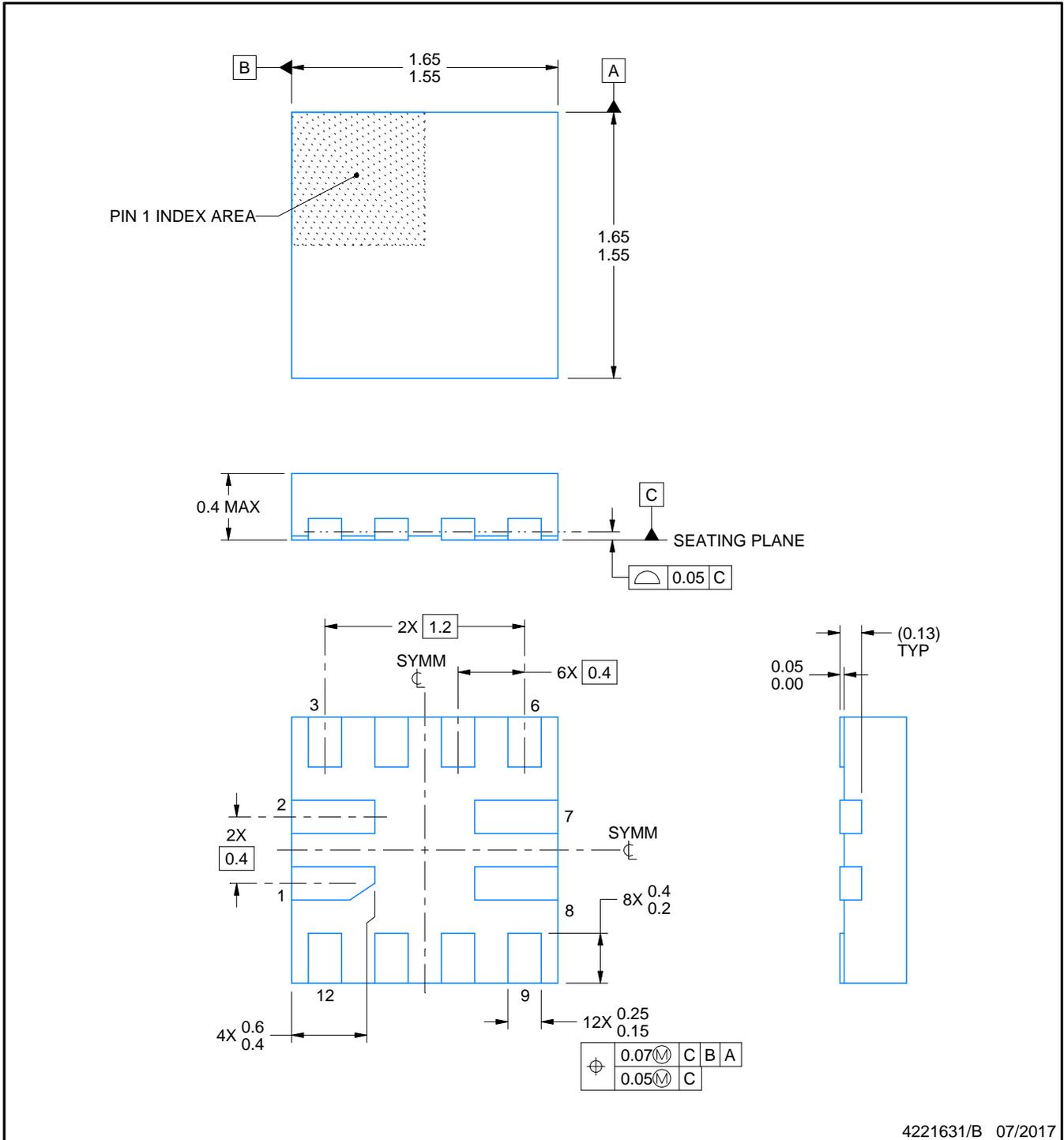

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TUSB3221RWBR	X2QFN	RWB	12	3000	180.0	8.4	1.8	1.8	0.61	4.0	8.0	Q2
TUSB3221RWBR	X2QFN	RWB	12	3000	180.0	8.4	1.8	1.8	0.48	4.0	8.0	Q2
TUSB3221RWBRG4	X2QFN	RWB	12	3000	180.0	8.4	1.8	1.8	0.48	4.0	8.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TUSB322IRWBR	X2QFN	RWB	12	3000	213.0	191.0	35.0
TUSB322IRWBR	X2QFN	RWB	12	3000	210.0	185.0	35.0
TUSB322IRWBRG4	X2QFN	RWB	12	3000	210.0	185.0	35.0



4221631/B 07/2017

NOTES:

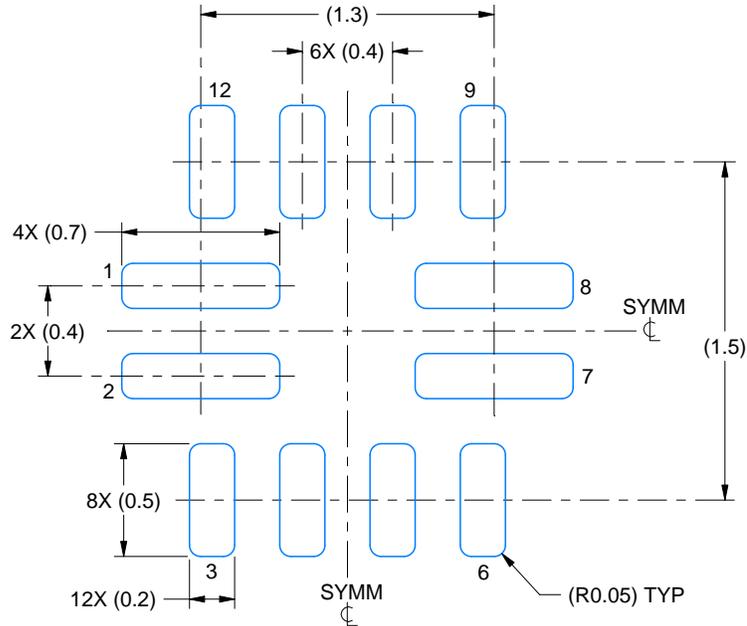
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

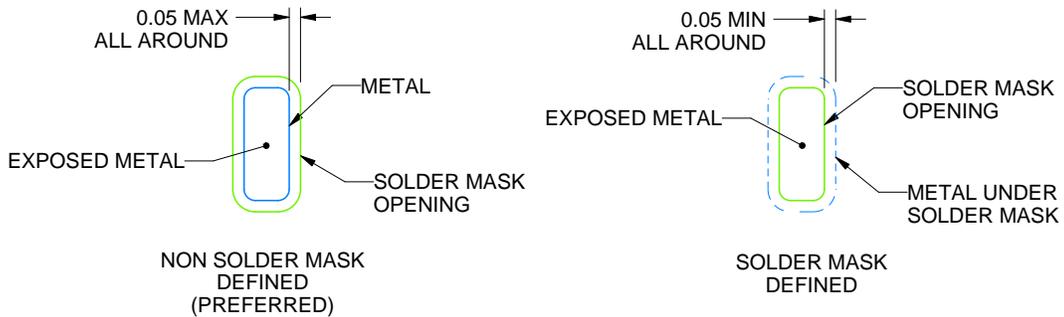
RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:30X



SOLDER MASK DETAILS

4221631/B 07/2017

NOTES: (continued)

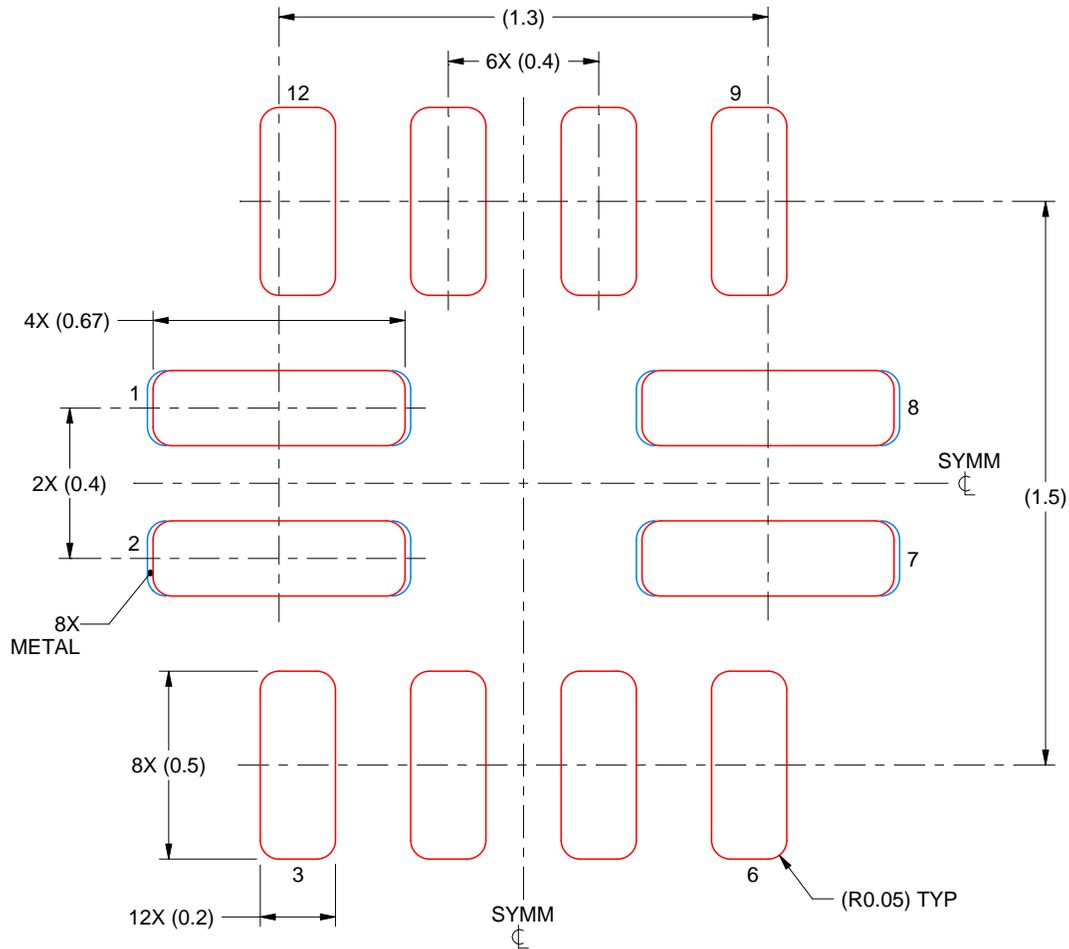
3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.1 mm THICK STENCIL  
PADS 1,2,7 & 8  
96% PRINTED SOLDER COVERAGE BY AREA  
SCALE:50X

4221631/B 07/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2025, Texas Instruments Incorporated